

ABSTRACT OF THE DISCLOSURE

A ground-enhanced semiconductor package and a lead frame used in the package are provided. The semiconductor package includes a lead frame having a die pad, a plurality of tie bars connected with and supporting the die pad, a plurality of leads surrounding the die pad, and a ground structure, wherein the ground structure comprises at least one of first ground portions connected to the tie bars, and/or at least one of second ground portions connected to the die pad, and wherein the first ground portions are separate from each other, and the second ground portions are separate from each other; at least one chip mounted on the die pad and electrically connected to the leads and the ground structure; and an encapsulation body for encapsulating the chip and the lead frame. The separately-arranged ground portions allow thermal stresses to be released from the ground structure without rendering deformation issues.

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